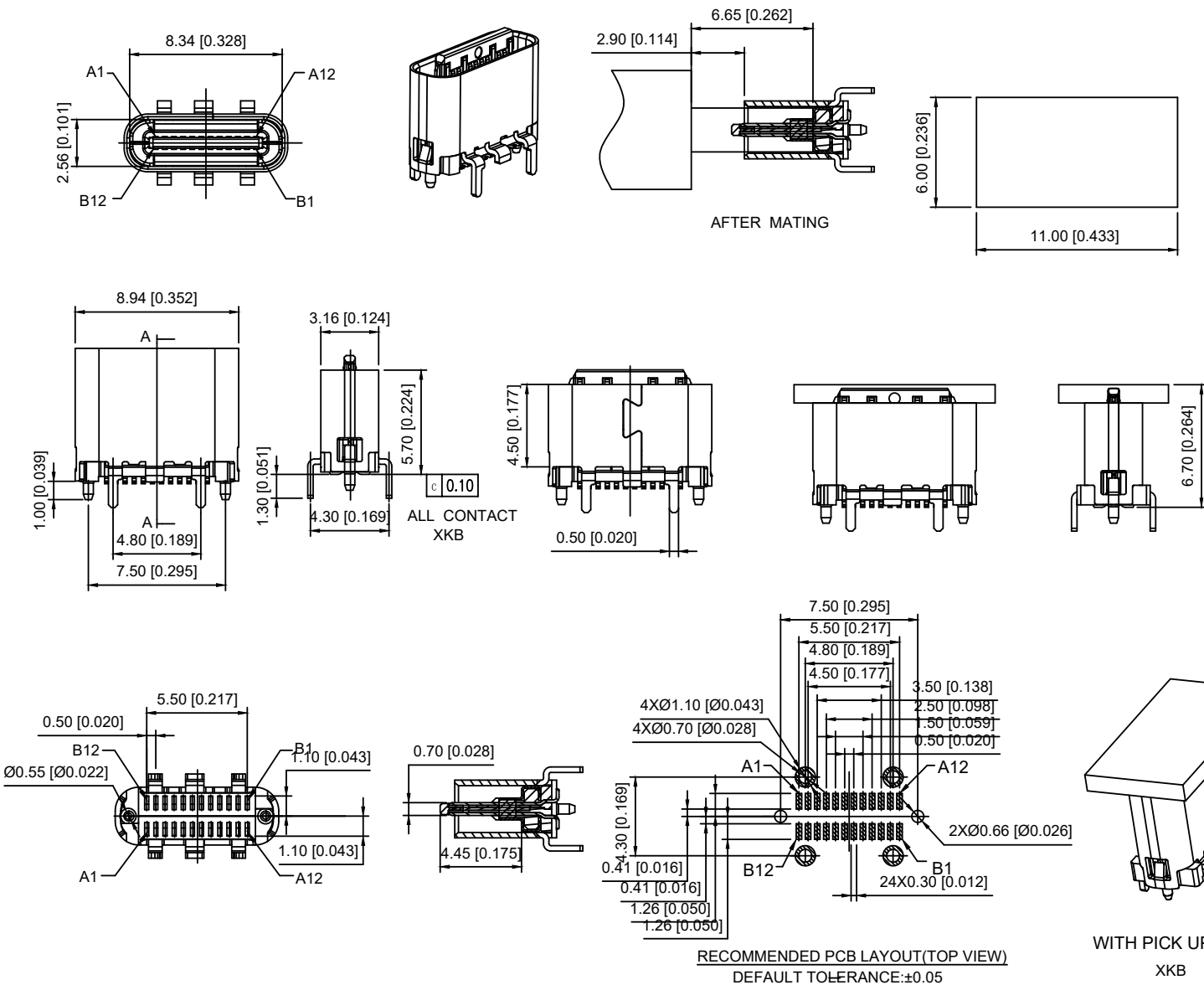




XKB CONNECTIVITY

XKB

NOTE:

- MATERIAL SPECIFICATION:
 - HOUSING: LCP, UL94 V-0.
 - TERMINAL: COPPER ALLOY
 - MID PLATE: STAINLESS STEEL
 - FRONT SHELL: STAINLESS STEEL
 - EMI PLATE: STAINLESS STEEL
- PLATING SPECIFICATION:
 - TERMINAL:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW THE P/N)
 - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - FRONT SHELL:
 - PLATING SPECIFICATIONS FOLLOW THE P/N
 - MID PLATE&EMI PLATE:
 - CLEAR ONLY
- MECHANICAL PERFORMANCE:
 - INSERTION FORCE: 0.5~2.0kgf.
 - REMOVAL FORCE: 0.8kgf~2.0kgf.
 - DURABILITY: 10000 CYCLES.
- ELECTRICAL PERFORMANCE:
 - VOLTAGE RATING: 5 V DC/AC (RMS. max)
 - CURRENT RATING: 5 AMPS. FOR TOTAL VBUS/GND PINS; 1.25AMPS FOR CC PIN, 0.25 AMPS. FOR ALL OTHER CONTACT.
 - LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
 - SHIELD: 50mΩ/MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 - INSULATION RESISTANCE: 100MΩ MIN
 - DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
- ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

XKB CONNECTIVITY

U263-241N-4BQC03

W: WHITE
B: BLACK

1: Au 1U"
2: Au 3U"
3: Au 15U"
4: Au 30U"

1: PBT
2: PA6T
3: PA9T
4: LCP

					ANGLAR	±5°
Δx					L≤ 4	±0.2
Δx					4<L≤ 16	±0.3
Δx					16<L≤ 63	±0.4
MARK	DESCRIPTION	DATE	REVISED	APPROVED	L> 63	±0.5
REVISIONS					UNSPECIFIED TOLERANCES	
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XKB

XKB INDUSTRIAL PRECISION CO., LIMITED

DSND		SCALE: N/A	MODEL TYPE: Type-C 3.1
DWN		VIEW:	PART NO.: U263-241N-4BQC03
CHKD		UNIT: mm/in	DWG NO.: X-U263-241N-4BQC03
APPD		SIZE: A4	WEIGHT SHEET REVISION
			1/1 A0